

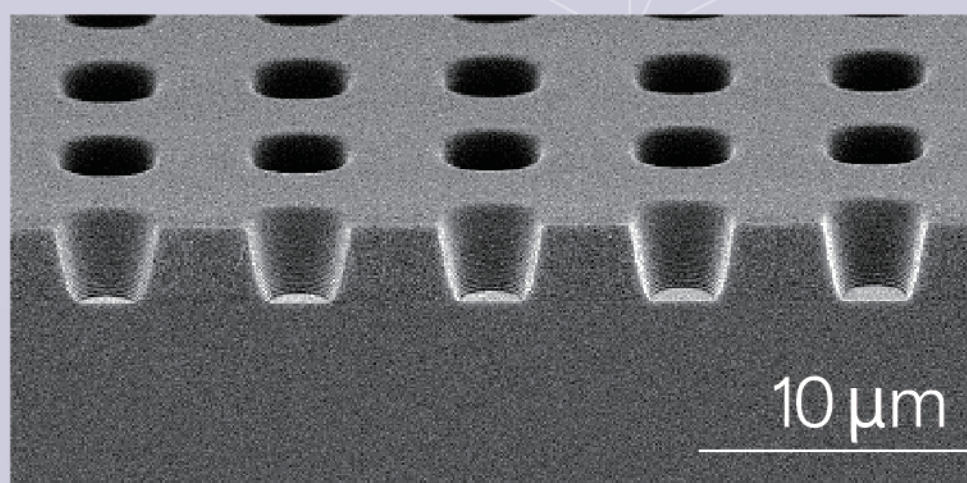
Photo-Imageable Dielectric (PID)

WPR Series / PFAS Free

Common Features

High resolution
Good adhesion
Low cure temperature

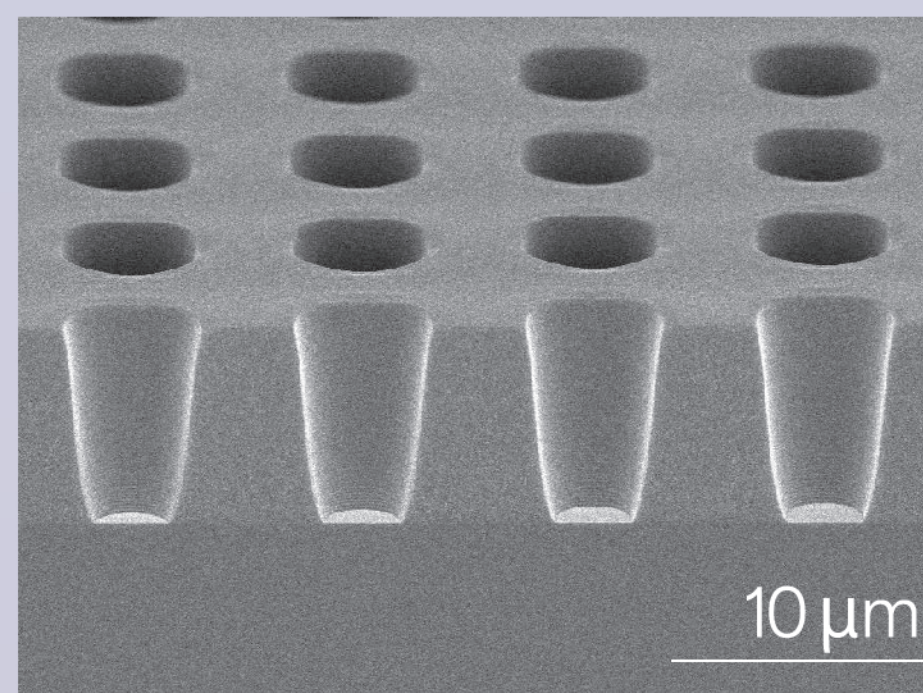
FT = 2 ~ 3 μm



2 μm -SQ

3 μm

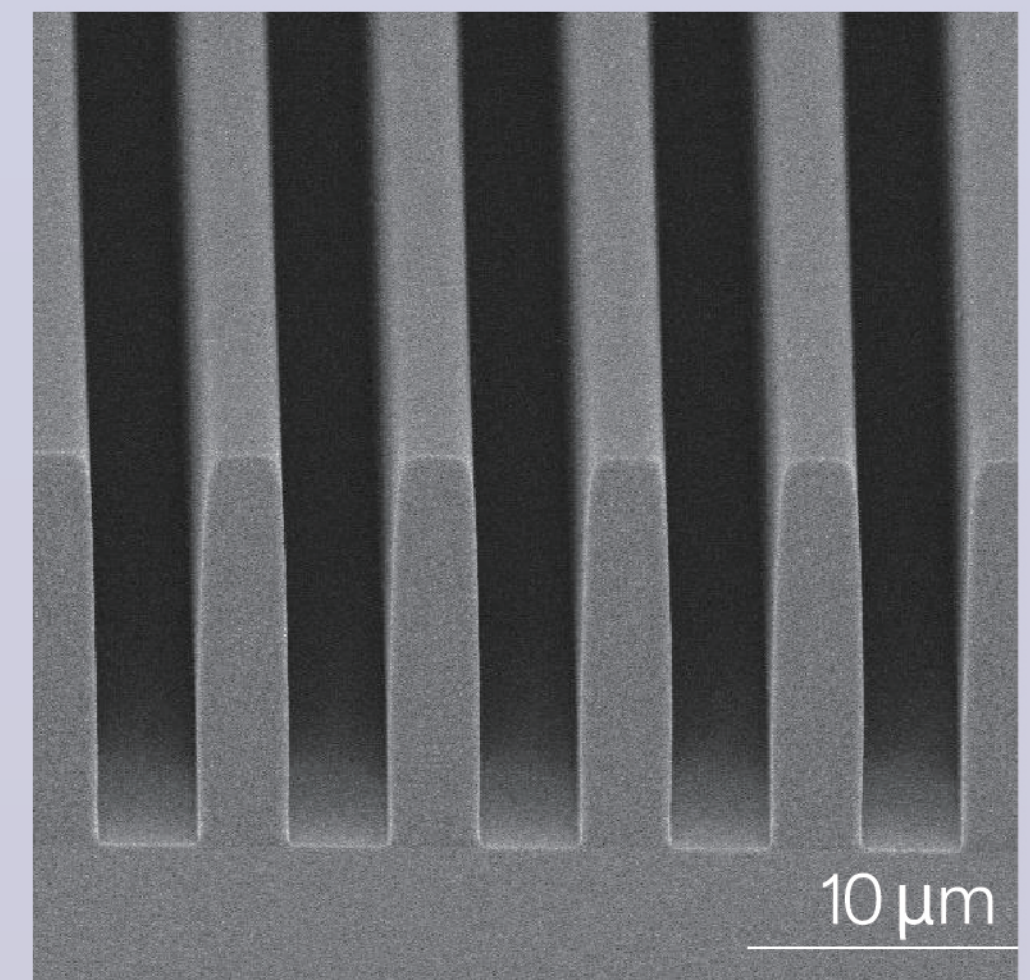
FT = 5 ~ 10 μm



2.5 μm -SQ

7 μm

FT = 10 ~ 20 μm



4 μm -L/S

15 μm

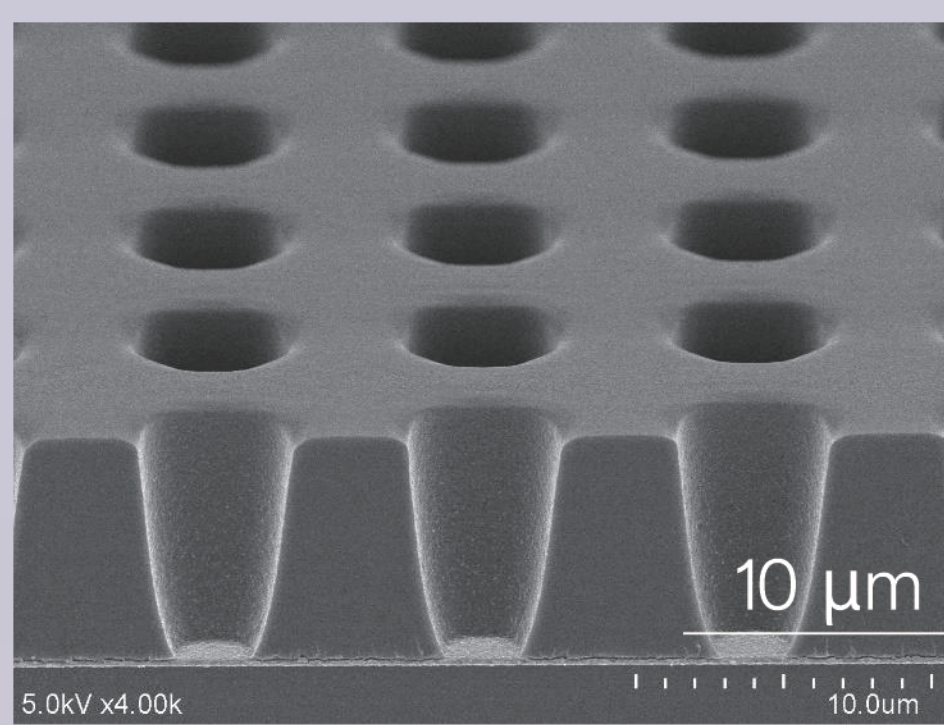
Positive-tone

- ✓ Photo-sensitivity for ghi-line
- ✓ Ideal taper profile

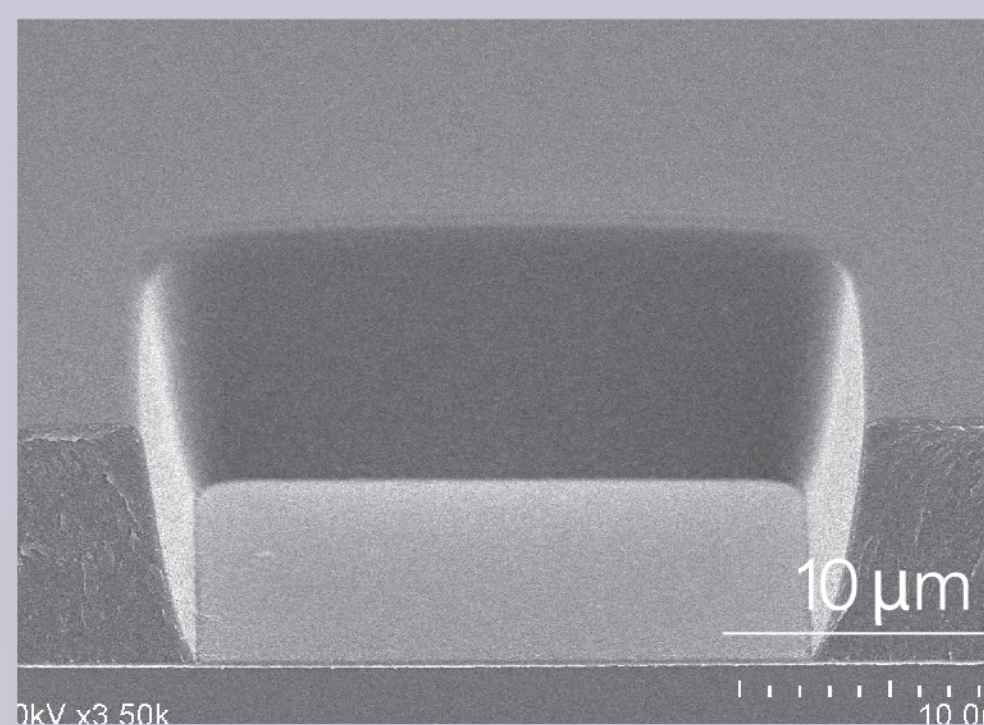
Negative-tone

- ✓ Thick patterning
- ✓ Low warpage

PI Series / PFAS Free - Under development



2.5 μm -SQ



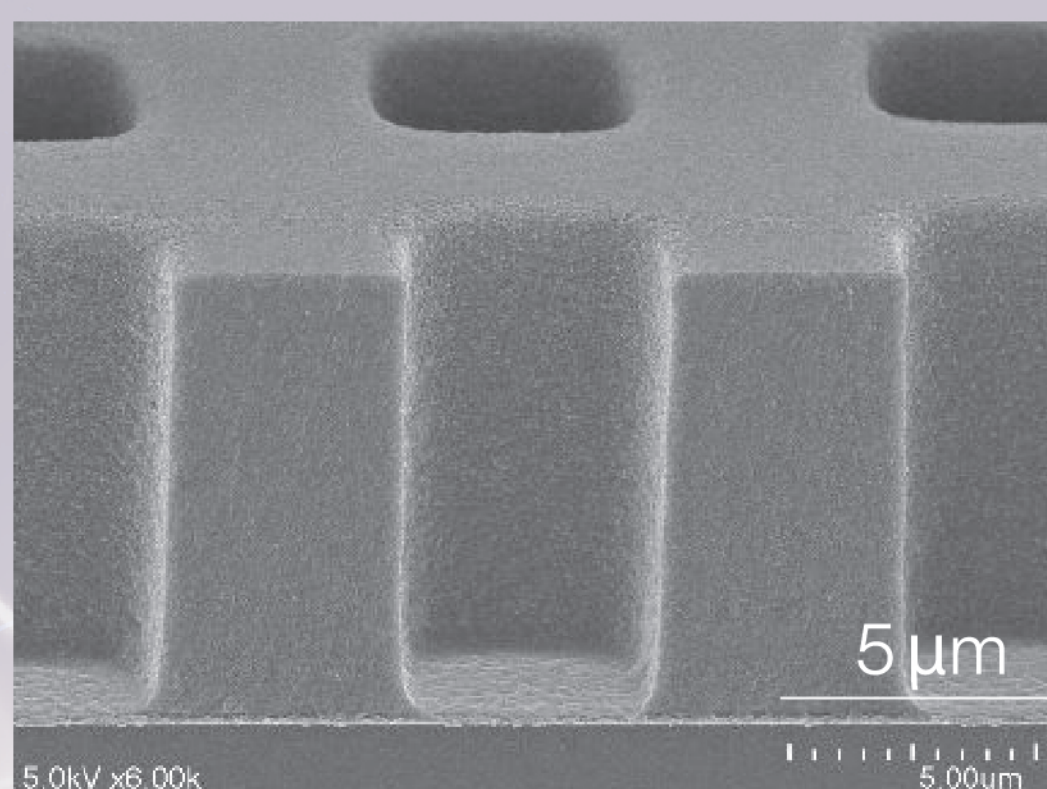
20 μm -SQ

7.5 μm

Positive-tone

- ✓ Low cure temperature ($\leq 200^\circ\text{C}$)
- ✓ Good elongation ($> 60\%$)
- ✓ High Tg (330°C)

Dry film PID - Under development



5 μm -SQ

10 μm

Negative - tone

- ✓ Dry film for advanced substrate
- ✓ Low CTE (31 ppm/K)
- ✓ Good Cu peel strength (0.4 N/mm)

